



BOARD CHARACTERISTICS

Copper Layer Count: 8 Board Thickness: 1.6180 mm
 Board overall dimensions: 130.0000 mm x 170.0000 mm
 Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.1500 mm
 Copper Finish: ENIG Impedance Control: Yes
 Castellated pads: No Plated Board Edge: No
 Edge card connectors: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Black	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric 1 (1/2)	prepreg	FR4-7628*1	0.218 mm	FR4 natural	4.4	0.02
Dielectric 1 (1/2)	prepreg	FR4-7628*1	0.203 mm	FR4 natural	4.4	0.02
PWR.Cu	copper		0.03 mm		1	0
Dielectric 2	core	FR4	0.075 mm	FR4 natural	4.6	0.02
signal1.Cu	copper		0.03 mm		1	0
Dielectric 3 (1/2)	prepreg	FR4-1080*1	0.069 mm	FR4 natural	3.91	0.02
Dielectric 3 (1/2)	prepreg	FR4-1080*1	0.069 mm	FR4 natural	3.91	0.02
signal2.Cu	copper		0.03 mm		1	0
Dielectric 4	core	FR4	0.075 mm	FR4 natural	4.6	0.02
signal3.Cu	copper		0.03 mm		1	0
Dielectric 5 (1/2)	prepreg	FR4-1080*1	0.069 mm	FR4 natural	3.91	0.02
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signal4.Cu	copper		0.03 mm		1	0
Dielectric 6	core	FR4	0.075 mm	FR4 natural	4.6	0.02
GND.Cu	copper		0.035 mm		1	0
Dielectric 7 (1/2)	prepreg	FR4-7628*1	0.203 mm	FR4 natural	4.4	0.02
Dielectric 7 (1/2)	prepreg	FR4-7628*1	0.218 mm	FR4 natural	4.4	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Black	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

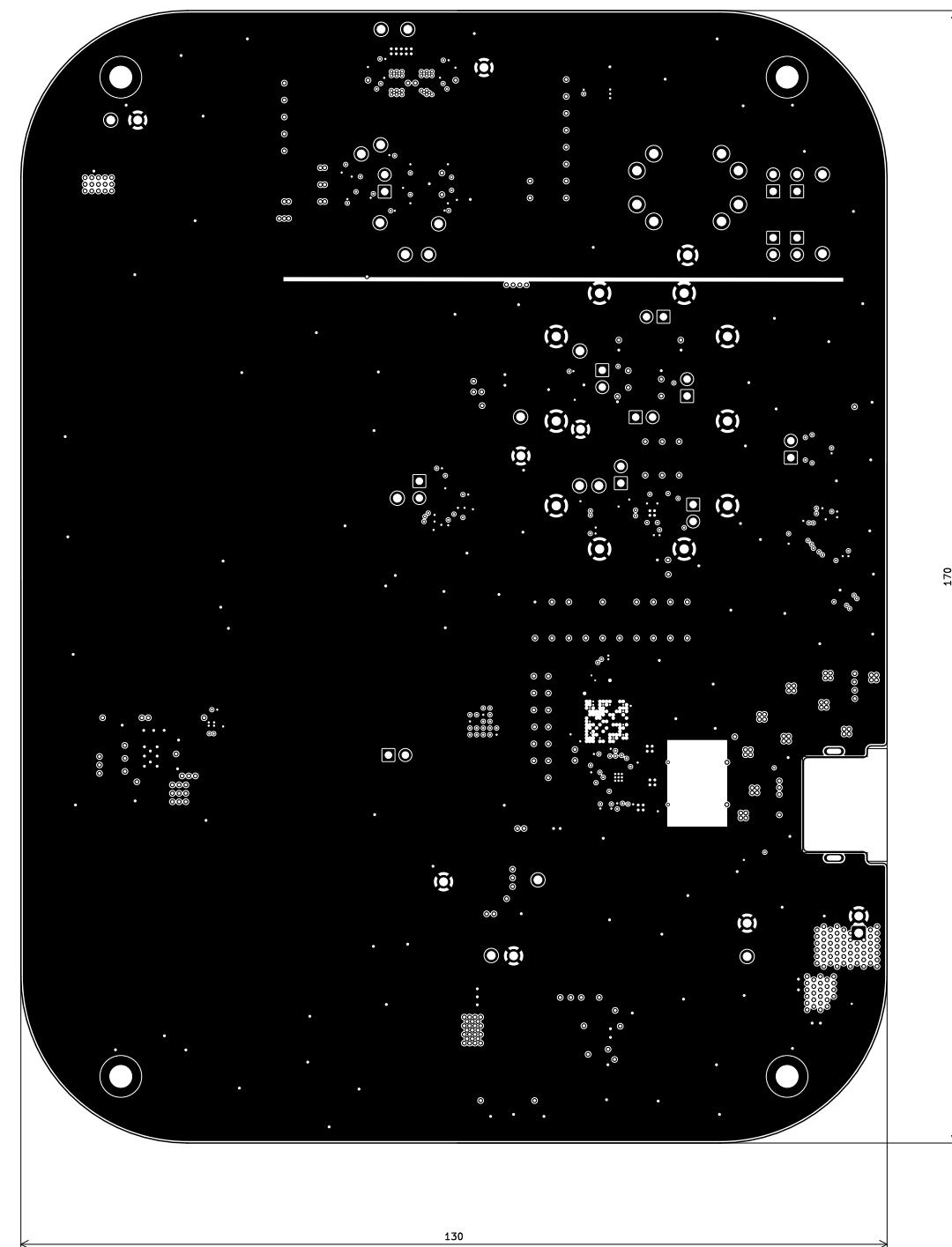
ORDERING NOTES

PCB:	* Product Type: Industrial/Consumer electronics * Different Design: 1 * Delivery Format: Single PCB * PCB Thickness: 1.6 mm * PCB Colour: Black * Silkscreen: White * Material Type: FR4—Standard TG 135–140 * Surface Finish: ENIG * Gold Thickness: 2 U"	PCB Advanced Options: * 4-Wire Kelvin Test: Yes * Paper Between PCBs: No * Appearance Quality: IPC Class 2 Standard * Silkscreen Technology: Ink-Jet/Screen Printing Silkscreen * Package Box: With JLCPCB Logo
PCBA:	* PCBA Type: Standard * Assembly Side: Both Sides * Edge Rails/Fiducials: Added by JLCPCB * Confirm Parts Placement: Yes * Parts Selection: By Customer	
PCBA Advanced Options:	* Photo Confirmation: No * Conformal Coating: No * Packaging: Antistatic Bubble Film * Solder Paste: Sn96.5%, Ag3.0%, Cu0.5% * Add Paste for Unpopulated Pad Opening: No * Others: No * Board Cleaning: No * Bake Components: No * Depanel Boards & Edge Rail Before Delivery: No * Flying Probe Test: No * Nitrogen Reflow Soldering: No	

Sheet:	File: PingDevKit.kicad_pcb
Title:	Sonar Development Board
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B							B
C							C
D							D
E							E

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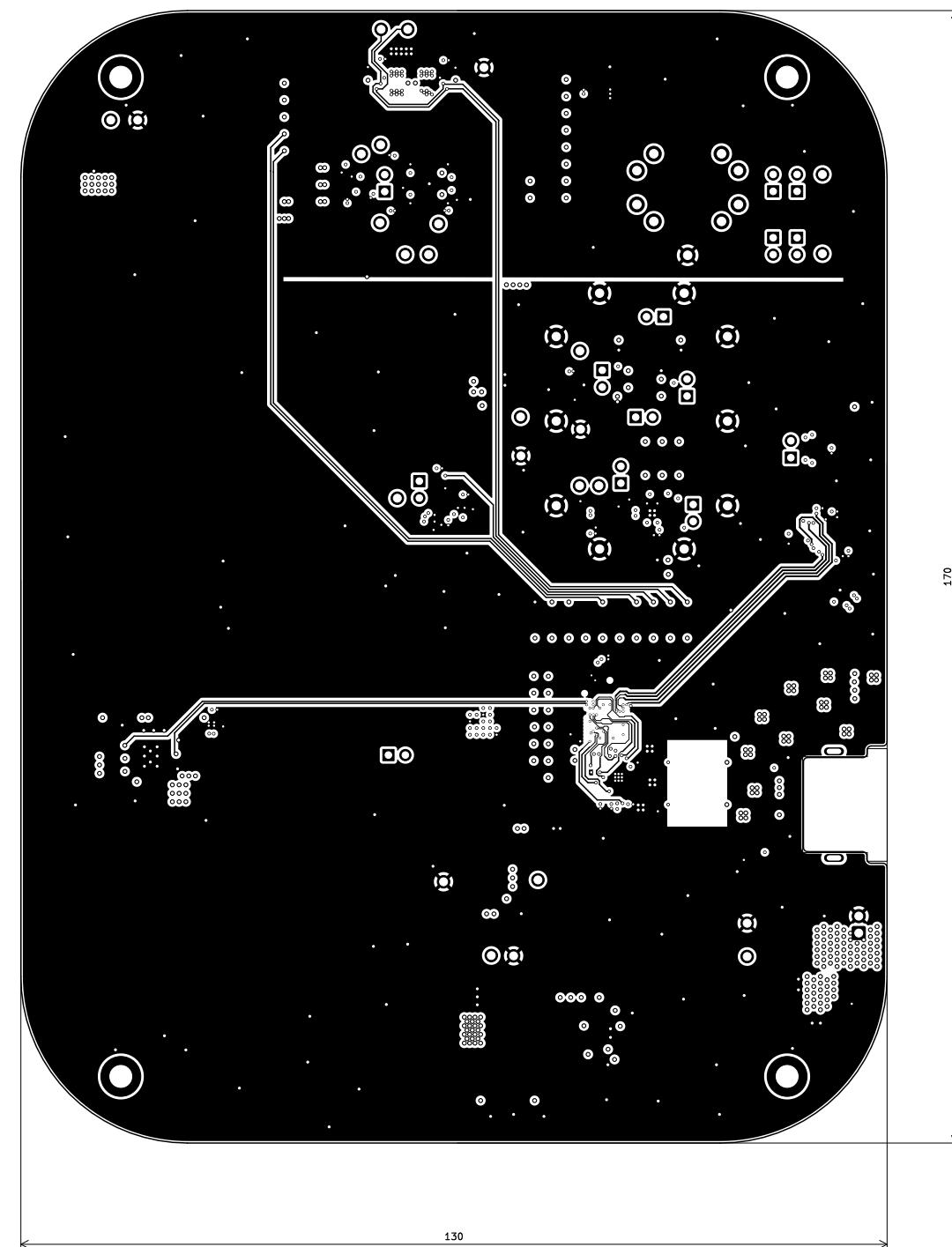
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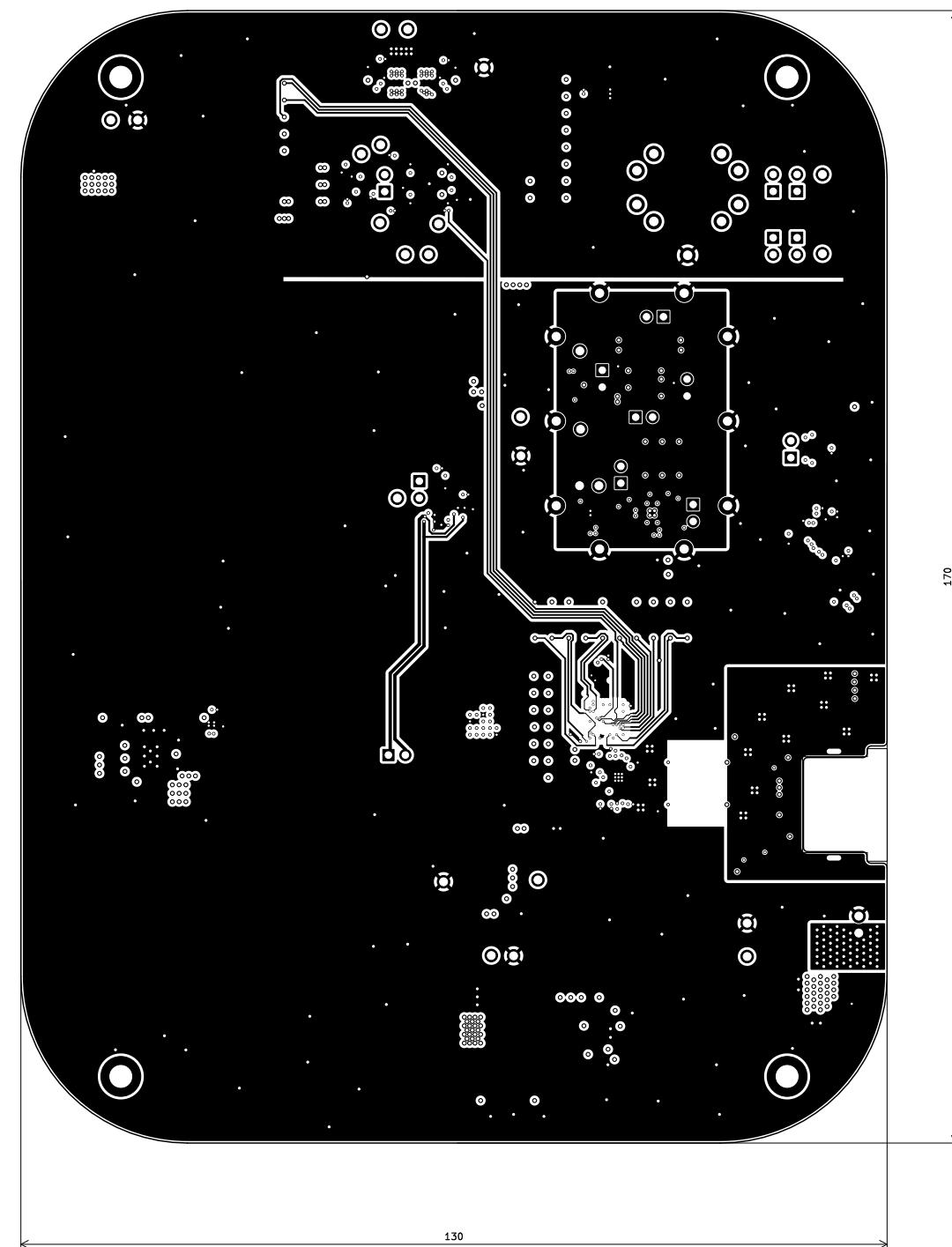
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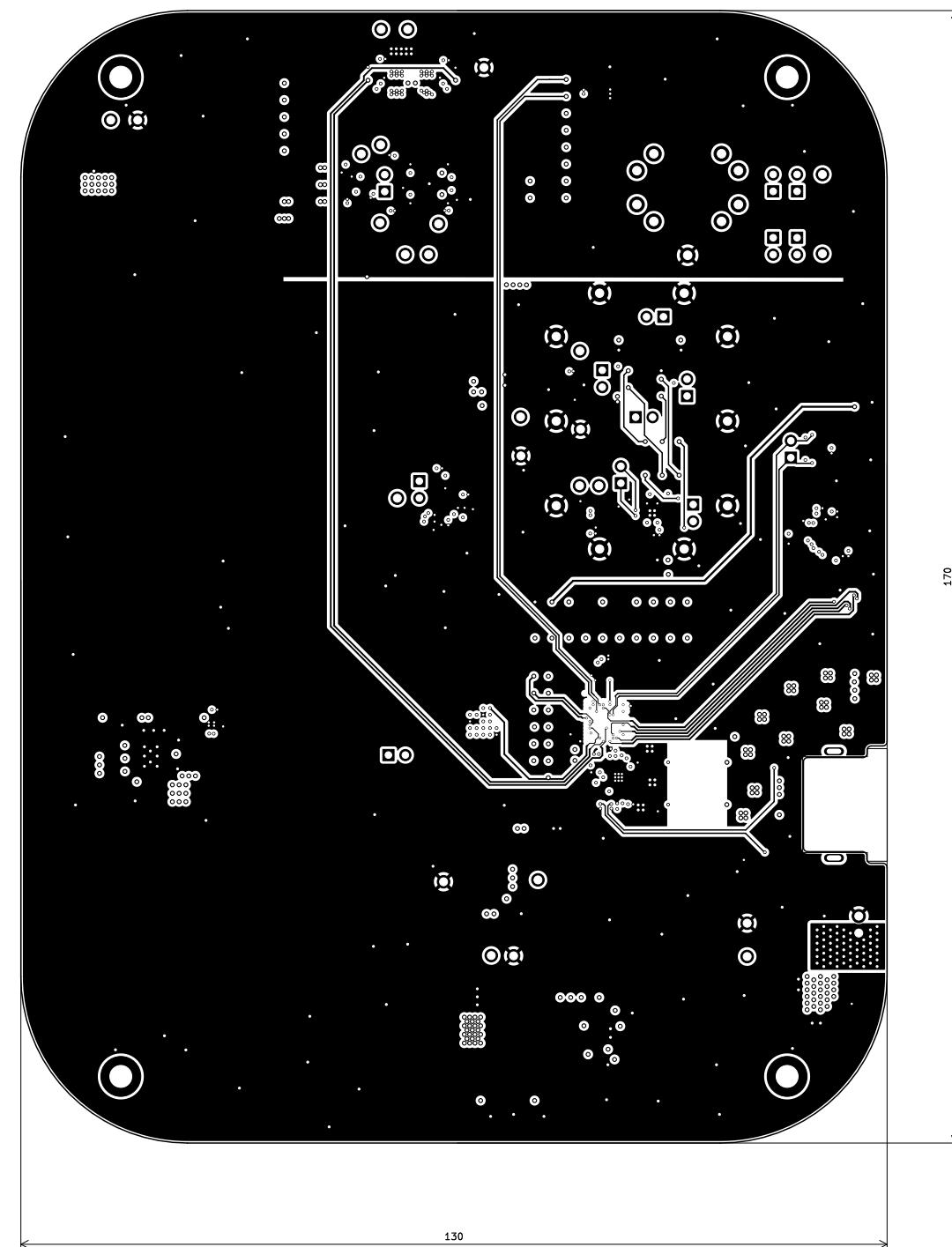
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